

ABSTRACT

An object of the present invention is to provide a resin composition which is capable of manufacturing a high dielectric resin film having high dielectric constant and small dielectric loss tangent. And the present invention provides high dielectric resin composition comprising:

a high dielectric filler; and
resin;

wherein a relative dielectric constant of the high dielectric filler satisfies the following formulae (1) and (2).

$$[(\epsilon_T - \epsilon_{25}) / \epsilon_{25}]_{\text{MAX}} \leq 0.03 \quad (1)$$

$$40 \leq \epsilon_{25} \leq 1000 \quad (2)$$